



PATENT APPLICATION

RESPONSE UNDER 37 C.F.R. §1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP 2822

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Kazutaka SHIBATA

Application No.: 09/814,057

Filed: March 22, 2001

For: SEMICONDUCTOR DEVICE WITH WARP PREVENTING BOARD JOINED  
THERETO (As Amended)

Attorney Docket No.: ROH-0034

Examiner: K. Rose

Art Unit: 2822

Confirmation No.: 2536

**AMENDMENT AFTER FINAL REJECTION UNDER 37 C.F.R. §1.116**

**BOX AF**

Commissioner for Patents  
Washington, DC 20231

Sir:

In response to the Office Action dated August 29, 2002, the period for response being extended to January 29, 2003, by the Petition for Extension of Time filed herewith, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please cancel claim 2 without prejudice or disclaimer.

Please amend claim 1 as set forth below in clean form. Additionally, in accordance with 37 CFR 1.121(c)(1)(ii), amended claim(s) is/are set forth in a marked-up version in the page(s) attached to this Amendment.

1. (Twice Amended) A semiconductor device comprising:
  - a semiconductor chip;
  - a wiring board joined to one surface of the semiconductor chip and electrically connected to the semiconductor chip, the wiring board having a wiring board thickness; and
  - a warp preventing board joined to the other surface of the semiconductor

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